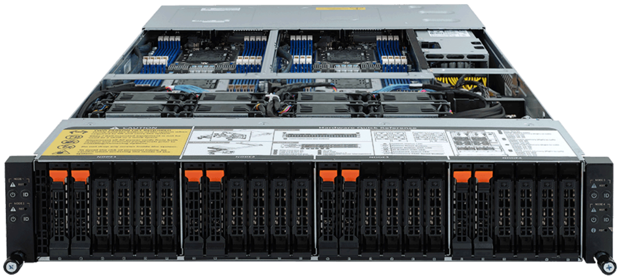
H262-Z63 (Rev. 100)

High Density Server - AMD EPYC™ 7002/7001 - 2U 4-Node DP 8-Bay NVMe/SATA



Key Features

- 2U 4-node rear access server system
- Dual AMD EPYC™ 7002/7001 Series Processors per node
- 8-Channel DDR4 RDIMM/LRDIMM, 16 x DIMMs per node
- 8 x 1 Gb/s LAN ports via Intel® I350-AM2
- 1 x CMC port
- 8 x 2.5" NVMe/SATA hot-swap bays
- 8 x M.2 slots with PCIe Gen3 x4 interface
- 8 x LP PCIe Gen4 x16 slots
- 4 x OCP 2.0 Gen3 x16 mezzanine slots
- Dual 2200 W 80 PLUS Platinum redundant power supplies

Applications

High Converged Server, Servers for Hybrid/Private Cloud...

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D840 mm)
Motherboard	MZ62-HD0
CPU	AMD EPYC™ 7002 Series Processors AMD EPYC™ 7001 Series Processors Dual processor per node, cTDP up to 240 W - At 25°C ambient, cTDP up to 280 W *Contact our sales representatives or technical support for more details about supporting cTDP 280 W CPUs.
Socket	8 x LGA 4094 (Socket SP3)
Chipset	System on Chip
Memory	8-Channel DDR4 RDIMM/LRDIMM, 64 x DIMMs Up to 3200 MT/s
LAN	8 x 1 Gb/s LAN (4 x Intel® I350-AM2), Support NCSI 4 x 10/100/1000 Mb/s Management LAN 1 x CMC port
Video	Integrated in ASPEED® AST2500 x 4 - 4 x VGA ports
Storage	**Front hot-swap:** 8 x 2.5" NVMe/SATA **Internal M.2:** 8 x M.2 (2242/2260/2280/22110), PCIe Gen3 x4 [1] [1] CPU TDP is limited to 155 W when using M.2 drives.
RAID	Require RAID add-in cards
PCIe Expansion Slots	8 x LP x16 (Gen4 x16) 4 x OCP 2.0 mezzanine (Gen3 x16)(Type1, P1, P2, P3, P4), Support NCSI
I/O Ports	**Front:** 1 x CMC status LED **Rear:** 8 x USB 3.0, 4 x VGA, 8 x RJ45, 4 x MLAN, 1 x CMC port
Backplane Board	PCIe Gen4 x4 or SATA 6 Gb/s or SAS 12 Gb/s
TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM010
Power Supply	Dual 2200 W 80 PLUS Platinum redundant power supplies AC Input: 100-240 V *The system power supply requires C19 power cord.
System Management	ASPEED® AST2500 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
System Fans	8 x 80x80x38mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing)
Packaging Content	1 x H262-Z63 8 x CPU heatsinks 1 x 3-Section Rail kit
Ordering Part Numbers	6NH262Z63MR-00-1*
Optional Parts	- C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - M.2 expansion card - CMTP04R: 9CMTP04RNR-00* - Ring topology kit: 6NH262Z65SR-00-100

Learn more at: https://www.gigabyte.com/Enterprise

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